NOTES: UNLESS OTHERWISE SPECIFIED

1. SPECIFICATIONS/TOLERANCES:
   A. FABRICATE PER IPC-6012, CLASS 2, USING PROVIDED DATA FILES 600-XXXXX-01_01.TGZ OR 410-XXXXX-01_01.ZIP.
   B. ALL SPECIFICATIONS USED SHALL BE PER THEIR LATEST REVISIONS.
   C. THE DIMENSIONS OF CIRCUIT FEATURES IN THE PROVIDED DATA MAY BE ADJUSTED ONLY TO COMPENSATE FOR PROCESS TOLERANCES; ADDING, REMOVING OR RELOCATING CIRCUIT FEATURES, INCLUDING NON-FUNCTIONAL PADS, IS NOT ALLOWED, AND THE DESIGN OF ALL PLANE STRUCTURES MUST BE MAINTAINED TO ENSURE PROPER ELECTRICAL PERFORMANCE.
   D. REMOVE ALL BURRS AND BREAK SHARP EDGES, .381 [.015] MAX RADIUS.
   E. PARENTHETICAL INFORMATION IS FOR REFERENCE ONLY.
   F. REPAIR OF PCB DEFECTS IS NOT PERMITTED.

2. DIELECTRIC MATERIAL:
   A. DIELECTRIC MATERIAL SHALL BE PER IPC-4101/99, /124, /126 OR /129 (RoHS COMPLIANT EPOXY-GLASS).
   B. MINIMUM DIELECTRIC THICKNESS SHALL BE .051 [.002] FOR REFERENCED STACK-UP DIMENSIONS OF.076 [.003] OR GREATER; IPC-6012 REQUIREMENTS SHALL OTHERWISE APPLY. SINGLE-PLY CONSTRUCTION IS ALLOWED.
   C. SEE LAYER STACK-UP FOR REQUIRED COPPER WEIGHTS AND THE FINISHED PCB THICKNESS. IF SPECIFIED, 1/3 OZ. STARTING FOIL MAY BE ACHIEVED BY 1/2 OZ. FOIL REDUCTION.
   D. FINISHED PCB THICKNESS SHALL BE MEASURED OVER LANDS AND/OR CONDUCTORS COVERED BY SOLDER MASK.
   E."MATERIAL TO BE USED IS 370HR"

3. DRILLING:
   A. VIA DIAMETERS (TOL. + +.051/- DRILL DIAMETER [+.0020/- DRILL DIAMETER]) SHALL BE VERIFIED BEFORE PLATING; ALL OTHER HOLE DIAMETERS SHALL BE VERIFIED AT FINAL INSPECTION.
   B. LAYER-TO-LAYER MISREGISTRATION SHALL BE .127 [.005] MAXIMUM.

4. SOLDER MASK:
   A. APPLY LPI SOLDER MASK USING PROVIDED DATA.
   B. SOLDER MASK SHALL BE PER IPC-SM-840, CLASS T, COLOR BLUE.
   C. THE DIMENSIONS OF SOLDER MASK-DEFINED PADS ON PLANES AND/OR WIDE CONDUCTORS SHALL NOT BE MODIFIED.

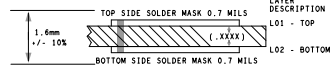
5. MARKING:
   A. MARK PCB PER PROVIDED DATA USING SILKSCREEN OR AUTOMATED INJET PROCESSING WITH PERMANENT, NON-CONDUCTIVE INK, COLOR WHITE.
   B. SUPPLIER ID AND TRACEABILITY INFORMATION SHALL BE APPLIED USING PERMANENT, NON-CONDUCTIVE INK, COLOR WHITE.
   C. INK SHALL NOT BE APPLIED TO ANY SOLDERABLE SURFACE.

6. ELECTRICAL TEST:
   A. DESIGN VERIFICATION SHALL BE DONE PRIOR TO PCB FABRICATION USING SUPPLIED VALOR ODB++ DATABASE, OR GERBER DATA AND AN IPC-D-356 NETLIST.
   B. ALL PCBS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS USING PROVIDED DATA.
7. C. APPLY TEST STAMP IN NON-LEGEND AREA ON REAR SIDE OF PCB; OK TO APPLY TO PANEL RAILS IF SPACE DOES NOT PERMIT.

   FINAL FINISH:
   A. FINAL FINISH SHALL BE ELECTROLESS NICKEL/IMMERSION GOLD (ENIG) PER IPC-4552.

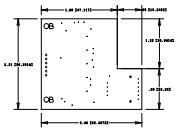
8. IMPEDANCE:
   A. IMPEDANCE TOLERANCE SHALL BE +/- 10%.
   B. SEE LAYER STACK-UP FOR IMPEDANCE REQUIREMENTS.

9. IF PANELIZATION SPECIFICATIONS ARE PROVIDED, THE PCBS SHALL BE DELIVERED IN PANEL FORM. HOWEVER, THESE SPECIFICATIONS MAY BE CHANGED AS REQUIRED BY THE CONTRACT MANUFACTURER TO SUPPORT VOLUME ASSEMBLY REQUIREMENTS.



LAYER DESCRIPTION	FINISH THICKNESS	SE IMP OHMS	SE TRACE WIDTH	REF LAYER	CPW SPACE	DIFF IMP OHMS	DIFF TRACE WIDTH/SPACE	REF LAYER	CPW SPACE
LO1 - TOP	1 OZ	--	.-----	---	-----	---	.----/.-----	---	-----
LO2 - BOTTOM	1 OZ	--	.-----	---	-----	---	.----/.-----	---	-----

STACK-UP



DRILL CHART: TOP to BOTTOM

SYM	DIAMETER	TOLERANCE (MIN)	TOLERANCE (MAX)	PLATED	QTY
•	0.3	+0.1/-0.0	PLATED	10	
◦	15.0	+0.1/-0.0	PLATED	10	
◆	40.007	+0.1/-0.0	PLATED	8	
■	97.000	+0.1/-0.0	NON-PLATED	3	
OB	120.0	+0.1/-0.0	NON-PLATED	2	

SEE BOM	SEE BOM		
NEXT ASSY	USED ON		
APPLICATION			

THE INFORMATION CONTAINED HEREIN IS CONFIDENTIAL AND PROPRIETARY TO CYPRESS SEMICONDUCTOR AND SHALL NOT BE REPRODUCED OR DISCLOSED IN WHOLE OR IN PART OR USED FOR ANY DESIGN, MANUFACTURE, OR OTHERWISE, EXCEPT WHEN SUCH USER POSSESSES AUTHORIZATION FROM CYPRESS.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN METRIC WITH INCHES IN BRACKETS
.XXX ±.004 [±.008] .XX ±.13 [±.01] ANGLES ±.5°

MATERIAL 2

FINISH 7

DO NOT SCALE DRAWING

APPROVALS	DATE
DRAWN: HUSA	16/10/23
ENGINEER: MANOHARAN	16/10/23
CHECKER: MANOHARAN	16/10/23
QA: -	-
PROJ. ENG. -	-

198 CHAMPION COURT
SAN JOSE, CA 95134
(408) 943-2600

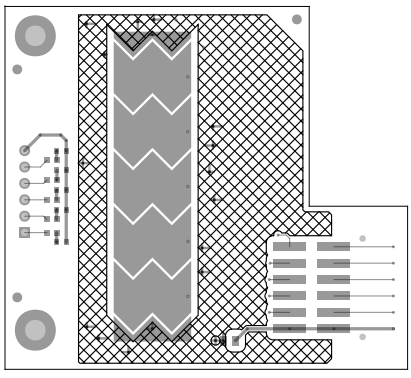
TITLE: PCB FABRICATION, RDK DOCK-CAPSENSE SLIDER ADDON BOARD

SIZE	CAGE CODE	DWG P/N
D	-	610-XXXXXX-01

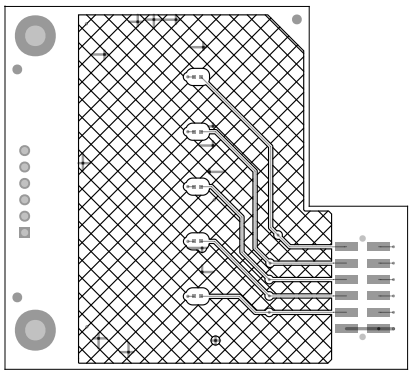
SCALE	SHEET	REV
1/1	1 OF 1	02

COMPUTER GENERATED DRAWING
DO NOT CHANGE MANUALLY

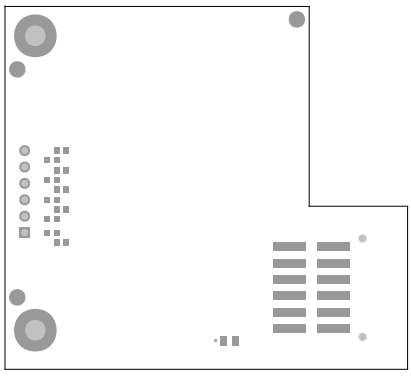
FAB NOTES REV 04/05/17



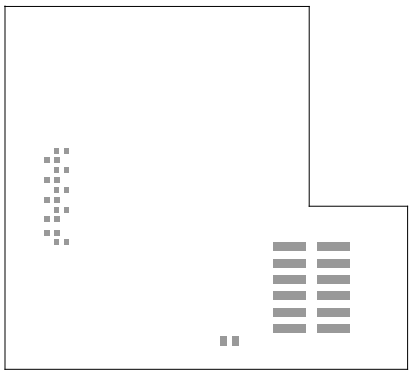
Infineon SAN JOSE, CA 95134 (408) 943-2600	PROJECT: RDK DOCK-CAPSENSE SLIDER ADDON BOARD		
	DRAWN BY: HUSA		
	LAYER: 01_TOP		
	DWG NO: 610-XXXXX-01	REV: 02	DATE: 16/10/23



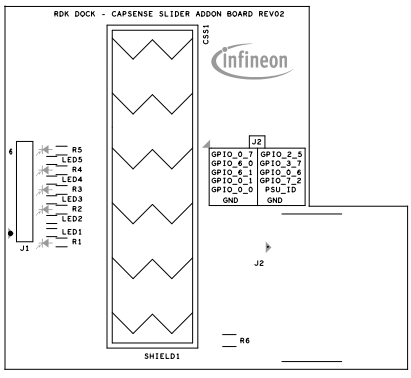
Infineon SAN JOSE, CA 95134 (408) 943-2600	PROJECT: RDK DOCK-CAPSENSE SLIDER ADDON BOARD		
	DRAWN BY: HUSA		
	LAYER: BOTTOM		
	DWG NO: 610-XXXXX-01	REV: 02	DATE: 16/10/23



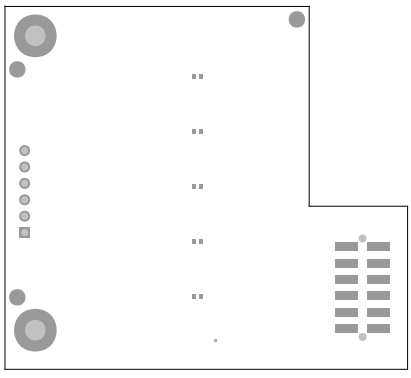
Infineon SAN JOSE, CA 95134 (408) 943-2600	PROJECT: RDK DOCK-CAPSENSE SLIDER ADDON BOARD		
	DRAWN BY: HUSA		
	LAYER: SOLDERMASK TOP		
	DWG NO: 610-XXXXX-01	REV: 02	DATE: 16/10/23



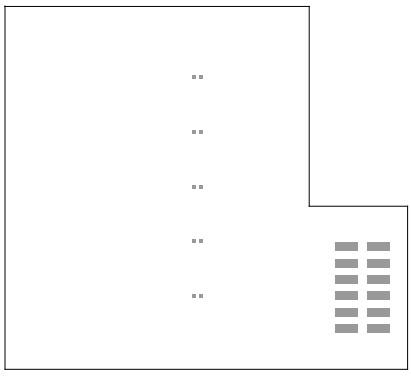
Infineon SAN JOSE, CA 95134 (408) 943-2600	PROJECT: RDK DOCK-CAPSENSE SLIDER ADDON BOARD		
	DRAWN BY: HUSA		
	LAYER: PASTEMASK TOP		
	DWG NO: 610-XXXXX-01	REV: 02	DATE: 16/10/23



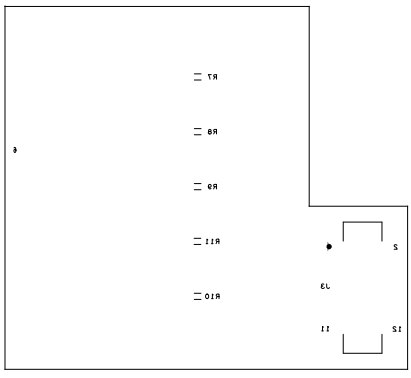
SAN JOSE, CA 95134 (408) 943-2600	PROJECT: RDK DOCK-CAPSENSE SLIDER ADDON BOARD		
	DRAWN BY: HUSA		
	LAYER: SILKSCREEN TOP		
	DWG NO: 610-XXXXX-01	REV: 02	DATE: 16/10/23



Infineon SAN JOSE, CA 95134 (408) 943-2600	PROJECT: RDK DOCK-CAPSENSE SLIDER ADDON BOARD		
	DRAWN BY: HUSA		
	LAYER: SOLDERMASK BOTTOM		
	DWG NO: 610-XXXXX-01	REV: 02	DATE: 16/10/23



Infineon SAN JOSE, CA 95134 (408) 943-2600	PROJECT: RDK DOCK-CAPSENSE SLIDER ADDON BOARD		
	DRAWN BY: HUSA		
	LAYER: PASTEMASK BOTTOM		
	DWG NO: 610-XXXXX-01	REV: 02	DATE: 16/10/23



Infineon SAN JOSE, CA 95134 (408) 943-2600	PROJECT: RDK DOCK-CAPSENSE SLIDER ADDON BOARD		
	DRAWN BY: HUSA		
	LAYER: SILKSCREEN BOTTOM		
	DWG NO: 610-XXXXX-01	REV: 02	DATE: 16/10/23